OKI Semiconductor

This version: Aug. 1998 Previous version: Nov. 1996

MSM7578H/7578V/7579

Single Rail CODEC

GENERAL DESCRIPTION

The MSM7578 and MSM7579 are single-channel CODEC CMOS ICs for voice signals ranging from 300 to 3400 Hz. These devices contain filters for A/D and D/A conversion. Designed especially for a single-power supply and low-power applications, these devices are particularly optimized for telephone terminals in digital wireless systems and ISDN systems. The devices use the same transmission clocks as those used in the MSM7508B and MSM7509B. The analog output signal can directly drive a piezoelectric type handset receiver.

FEATURES

- Single power supply: +5.0 V ±5%
- Low power consumption

Operating mode: $25 \text{ mW Typ.} \quad 47 \text{ mW Max.} \quad V_{DD} = 5 \text{ V}$ Power down mode: $0.05 \text{ mW Typ.} \quad 0.3 \text{ mW Max.} \quad V_{DD} = 5 \text{ V}$

• ITU-T Companding law

MSM7578H: μ-law MSM7579: A-law

MSM7578V: μ /A-law pin-selectable

- Built-in PLL eliminates a master clock
- Serial data rate: 64/128/256/512/1024/2048 kHz 96/192/384/768/1536/1544/200 kHz
- Adjustable transmit gain
- Built-in reference voltage supply
- Directly drive a line transformer of 600 Ω
- The 16-pin DIP and 24-pin SOP package products provide pin compatibility with the MSM7508B/ 7509B
- The 20-pin SSOP package products have 1/3 the foot print of conventional products
- Package options:

16-pin plastic DIP (DIP16-P-300-2.54) (Product name : MSM7578HRS)

(Product name : MSM7579RS) (Product name : MSM7578VRS)

24-pin plastic SOP (SOP24-P-430-1.27-K) (Product name: MSM7578HGS-K)

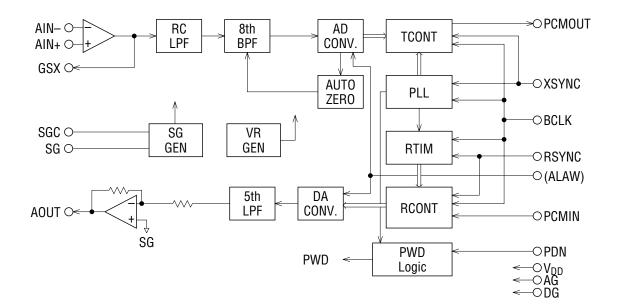
(Product name : MSM7578VGS-K) (Product name : MSM7579GS-K)

20-pin plastic SSOP (SSOP20-P-250-0.95-K) (Product name: MSM7578HMS-K)

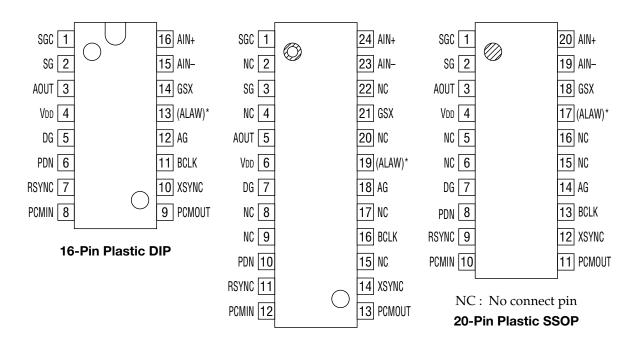
(Product name : MSM7579MS-K)

(Product name: MSM7578VMS-K)

BLOCK DIAGRAM



PIN CONFIGURATION (TOP VIEW)



NC: No connect pin **24-Pin Plastic SOP**

 $^{^{\}ast}$ The ALAW pin is only applied to the MSM7578VRS/MSM7578VGS-K/MSM7578VMS-K.

PIN AND FUNCTIONAL DESCRIPTIONS

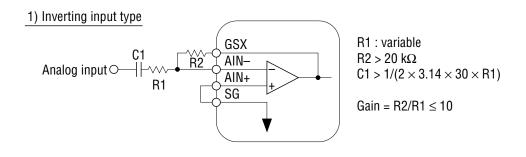
AIN+, AIN-, GSX

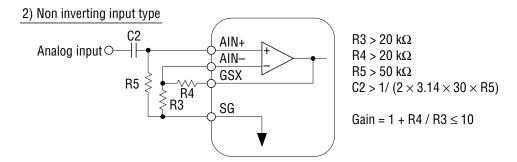
Transmit analog input and transmit level adjustment.

AIN+ is a non-inverting input to the op-amp; AIN- is an inverting input to the op-amp; GSX is connected to the output of the op-amp and is used to adjust the level, as shown below.

When not using AIN- and AIN+ connect AIN- to GSX and AIN+ to SG. During power saving

When not using AIN– and AIN+, connect AIN– to GSX and AIN+ to SG. During power saving and power down modes, the GSX output is at AG voltage.





AG

Analog signal ground.

AOUT

Analog output.

The output signal has a maximum amplitude of 2.4 V_{PP} above and below the signal ground voltage ($V_{DD}/2$).

The output load resistance is a minimum of 600 Ω .

During power saving, or power down mode, the output of AOUT is at the voltage level of the signal ground.

V_{DD}

Power supply for +5 V.

PCMIN

PCM signal input.

A serial PCM signal input to this pin is converted to an analog signal in synchronization with the RSYNC signal and BCLK signal.

The data rate of the PCM signal is equal to the frequency of the BCLK signal.

The PCM signal is shifted at a falling edge of the BCLK signal and latched into the internal register when shifted by eight bits.

The start of the PCM data (MSD) is identified at the rising edge of RSYNC.

BCLK

Shift clock signal input for the PCMIN and PCMOUT signal.

The frequency, equal to the data rate, is 64, 96, 128, 192, 256, 384, 512, 768, 1024, 1536, 1544, 2048, or 200 kHz. Setting this signal to logic "1" or "0" drives both transmit and receive circuits to the power saving state.

RSYNC

Receive synchronizing signal input.

Eight required bits are selected from serial PCM signals on the PCMIN pin by the receive synchronizing signal.

Signals in the receive section are synchronized by this synchronizing signal. This signal must be synchronized in phase with the BCLK. The frequency should be 8 kHz ±50 ppm to guarantee the AC characteristics which are mainly the frequency characteristics of the receive section.

However, if the frequency characteristic of an applied system is not specified exactly, this device can operate in the range of $8\,\mathrm{kHz}\pm2\,\mathrm{kHz}$, but the electrical characteristics in this specification are not guaranteed.

XSYNC

Transmit synchronizing signal input.

The PCM output signal from the PCMOUT pin is output in synchronization with this transmit synchronizing signal. This synchronizing signal triggers the PLL and synchronizes all timing signals of the transmit section.

This synchronizing signal must be synchronized in phase with BCLK.

The frequency should be 8 kHz ±50 ppm to guarantee the AC characteristics which are mainly the frequency characteristics of the transmit section.

However, if the frequency characteristic of an applied system is not specified exactly, this device can operate in the range of 8 kHz ±2 kHz, but the electrical characteristics in this specification are not guaranteed.

Setting this signal to logic "1" or "0" drives both transmit and receive circuits to the power saving state.

DG

Ground for the digital signal circuits.

This ground is separate from the analog signal ground. The DG pin must be connected to the AG pin on the printed circuit board to make a common analog ground.

PDN

Power down control signal.

A logic "0" level drives both transmit and receive circuits to a power down state.

PCMOUT

PCM signal output.

The PCM output signal is output from MSD in a sequential order, synchronizing with the rising edge of the BCLK signal.

MSD may be output at the rising edge of the XSYNC signal, based on the timing between BCLK and XSYNC.

This pin is in a high impedance state except during 8-bit PCM output. It is also in a high impedance state during power saving or power down mode.

A pull-up resistor must be connected to this pin because its output is configured as an open drain. This device is compatible with the ITU-T recommendation on coding law and output coding format.

The MSM7579 (A-law) outputs the character signal, inverting the even bits.

Innert Outrout Lavel	PCMIN/PCMOUT								
Input/Output Level	MSM7578H (μ-law)	MSM7579 (A-law)							
	MSD	MSD							
+Full scale	1 0 0 0 0 0 0 0	1 0 1 0 1 0 1 0							
+0	1 1 1 1 1 1 1 1	1 1 0 1 0 1 0 1							
-0	0 1 1 1 1 1 1 1	0 1 0 1 0 1 0 1							
–Full scale	0 0 0 0 0 0 0 0	0 0 1 0 1 0 1 0							

SG

Signal ground voltage output.

The output voltage is 1/2 of the power supply voltage.

The output drive current capability is $\pm 300 \, \mu A$.

This pin provides the SG level for CODEC peripherals.

This output voltage level is undefined during power saving or power down mode.

SGC

Used to generate the signal ground voltage level by connecting a bypass capacitor. Connect a $0.1\,\mu F$ capacitor with excellent high frequency characteristics between the AG pin and the SGC pin.

ALAW

Control signal input of the companding law selection.

Provides only for the MSM7578VRS/7578VGS-K/7578VMS-K. The CODEC will operate in the μ -law when this pin is at a logic "0" level and the CODEC will operate in the A-law when this pin is at a logic "1" level. The CODEC operates in the μ -law if the pin is left open, since the pin is internally pulled down.

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Rating	Unit
Power Supply Voltage	V _{DD}	_	0 to 7	V
Analog Input Voltage	V _{AIN}	_	-0.3 to V _{DD} + 0.3	V
Digital Input Voltage	V _{DIN}	_	-0.3 to V _{DD} + 0.3	V
Storage Temperature	T _{STG}	_	-55 to +150	°C

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	V_{DD}	Voltage must be fixed	4.75	5	5.25	V
Operating Temperature	Ta	_	-30	+25	+85	°C
Analog Input Voltage	V _{AIN}	Connect AIN- and GSX	_	_	2.4	V _{PP}
Input High Voltage	V _{IH}	XSYNC, RSYNC, BCLK,	2.2	_	V _{DD}	V
Input Low Voltage	V _{IL}	PCMIN, PDN, ALAW	0	_	0.8	V
			64, 128, 2	256, 512, 1	024,	
Clock Frequency	F _C	BCLK	2048, 96,	192, 384,	768,	kHz
			1536, 154			
Sync Pulse Frequency	F _S	XSYNC, RSYNC	6.0	8.0	9.0	kHz
Clock Duty Ratio	D _C	BCLK	40	50	60	%
Digital Input Rise Time	t _{lr}	XSYNC, RSYNC, BCLK,	_	_	50	ns
Digital Input Fall Time	t _{lf}	PCMIN, PDN, ALAW	_	_	50	ns
Transmit Cyna Dulas Catting Time	t _{XS}	BCLK→XSYNC, See Timing Diagram	100	_		ns
Transmit Sync Pulse Setting Time	t _{SX}	XSYNC→BCLK, See Timing Diagram	100	_	_	ns
Receive Sync Pulse Setting Time	t _{RS}	BCLK→RSYNC, See Timing Diagram	100	_		ns
neceive Sync Pulse Selling Time	t _{SR}	RSYNC→BCLK, See Timing Diagram	100	_		ns
Sync Pulse Width	tws	XSYNC, RSYNC	1 BCLK	_	100	μS
PCMIN Set-up Time	t _{DS}	_	100			ns
PCMIN Hold Time	t _{DH}		100	_		ns
Digital Output Load	R _{DL}	Pull-up resistor	0.5	_	_	kΩ
Digital Output Load	C_{DL}	_	_	_	100	pF
Analog Input Allowable DC Offset		Transmit gain stage, Gain= 1	-100	_	+100	mV
Analog Input Allowable DC Offset	V _{off}	Transmit gain stage, Gain = 10	-10	_	+10	mV
Allowable Jitter Width	_	XSYNC, RSYNC, BCLK		_	1	μS

ELECTRICAL CHARACTERISTICS

DC and Digital Interface Characteristics

 $(V_{DD} = +5 \text{ V } \pm 5\%, \text{ Ta} = -30^{\circ}\text{C to } +85^{\circ}\text{C})$

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Current	I _{DD1}	Operating mode, No signal	_	5	9	mA
	I _{DD2}	Power-down mode, PDN = 0		0.01	0.05	mA
		Power-save mode, PDN = 1,		1.0	2.0	A
	I _{DD3}	$XSYNC \rightarrow OFF$	_	1.2	3.0	mA
Input High Voltage	V _{IH}	_	2.2	_	V_{DD}	V
Input Low Voltage	V _{IL}	_	0.0	_	0.8	V
High Level Input Leakage Current	I _{IH}	_	_	_	2.0	μΑ
Low Level Input Leakage Current	I _{IL}	_	_	_	0.5	μΑ
Digital Output Low Voltage	V _{OL}	Pull-up resistance $> 500 \Omega$	0.0	0.2	0.4	V
Digital Output Leakage Current	I ₀	-	_	_	10	μΑ
Input Capacitance	C _{IN}	<u> </u>	_	5	_	pF
Analog Input Resistance	R _{IN}	AIN+, AIN-	_	10	_	MΩ

Transmit Analog Interface Characteristics

 $(V_{DD} = +5 \text{ V to } \pm 5\%, \text{ Ta} = -30^{\circ}\text{C to } +85^{\circ}\text{C})$

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Parameter	Symbol	Cond	dition	Min.	Тур.	Max.	Unit
Input Resistance	R _{INX}	AIN+, AIN-		10			MΩ
Output Load Resistance	R _{LGX}	GSX with respe	20	_	_	kΩ	
Output Load Capacitance	C _{LGX}			_	_	30	pF
Output Amplitude	V _{OGX}			-1.2	_	+1.2	V
Offset Voltage	Vosgx		Gain = 1	-20	_	+20	mV

Receive Analog Interface Characteristics

 $(V_{DD} = +5 \text{ V to } \pm 5\%, \text{ Ta} = -30^{\circ}\text{C to } +85^{\circ}\text{C})$

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Output Load Resistance	R _{LA0}	AOUT with respect to SG	0.6		_	kΩ
Output Load Capacitance	C _{LAO}	AOUT with respect to SG		_	50	pF
Output Amplitude	V _{OAO}	AOUT with respect to SG	-1.2	_	+1.2	V
Offset Voltage	V _{OSAO}	AOUT with respect to SG	-100		+100	mV

AC Characteristics

 $(V_{DD} = +5 \text{ V } \pm 5\%, \text{ Ta} = -30^{\circ}\text{C to } +85^{\circ}\text{C})$

Parameter	Symbol	Freq. (Hz)	Level (dBm0)	Condition	Min.	Тур.	Max.	Unit
	Loss T1	60			20	26	_	dB
	Loss T2	300			-0.15	+0.07	+0.20	dB
Transmit Frequency Response	Loss T3	1020				Reference		dB
	Loss T4	2020	0		-0.15	-0.04	+0.20	dB
	Loss T5	3000			-0.15	+0.06	+0.20	dB
	Loss T6	3400			0	0.4	0.80	dB
	Loss R1	300			-0.15	-0.03	+0.20	dB
	Loss R2	1020				Reference		dB
Receive Frequency Response	Loss R3	2020	0		-0.15	-0.02	+0.20	dB
	Loss R4	3000			-0.15	+0.15	+0.20	dB
	Loss R5	3400			0.0	0.4	0.80	dB
	SD T1		3		35	43	_	
	SD T2		0		35	41	_	dB
	SD T3		-30	*1	35	38		
Transmit Signal to Distortion Ratio	SD T4	1020	-40	*2	29	31		
					29	30		
	SD T5		-45	*2	24	27		
					24	26		
	SD R1		3		36	43		
	SD R2		0		36	41		
	SD R3		-30	*1	36	40		
Receive Signal to Distortion Ratio	SD R4	1020	-40	*2	30	33.5		dB
	SD N4				29	32	_	
	SD R5		–45	*2	25	30		
	טט מט		-4 5		24	27		
	GT T1		3		-0.3	+0.01	+0.3	
	GT T2		-10		Reference			
Transmit Gain Tracking	GT T3	1020	-40		-0.3	0	+0.3	dB
	GT T4		-50		-0.6	-0.13	+0.6	
	GT T5		-55		-1.2	-0.15	+1.2	
	GT R1		3		-0.3	0	+0.3	
Receive Gain Tracking	GT R2		-10			Reference		
	GT R3	1020	-40		-0.3	+0.10	+0.3	dB
	GT R4		-50		-0.6	+0.20	+0.6	
	GT R5		-55		-1.2	+0.25	+1.2	

^{*1} Psophometric filter is used

^{*2} Upper is specified for the MSM7578H, lower for the MSM7579

AC Characteristics (Continued)

 $(V_{DD} = +5 \text{ V } \pm 5\%, \text{ Ta} = -30^{\circ}\text{C to } +85^{\circ}\text{C})$

				,				
Parameter	Symbol	Freq. (Hz)	Level (dBm0)	Condition	Min.	Тур.	Max.	Unit
	Nidla T			AIN = SG		-72.5	-70	
Idle Channel Noise	Nidle T	_	_	*1 *2	_	-70.5	-68	dBm0p
	NidleR	_	_	*1 *3		-78	-75	
Absolute Level (Initial Difference)	AV T			$V_{DD} = 5.0 \text{ V}$ Ta = 25°C	0.5803	0.6007	0.6218	Vrms
Absolute Level (Illitial Difference)	AV R			1α – 25 0	0.5803	0.6007	0.6218	VIIIIS
Absolute Level (Deviation of Temperature and Power)	AV Tt	1020	0	V _{DD} = +5 V ±5%	-0.2	_	+0.2	dB
	AV Rt			Ta = -30 to 85°C	-0.2	_	+0.2	dB
Absolute Delay	Td	1020	0	A to A BCLK = 64 kHz	_	_	0.60	ms
	tgd T1	500		*4	_	0.19	0.75	
	tgd T2	600			_	0.11	0.35	
Transmit Group Delay	tgd T3	1000	0		_	0.02	0.125	ms
	tgd T4	2600			_	0.05	0.125	
	tgd T5	2800			_	0.07	0.75	
	tgd R1	500		*4	_	0.00	0.75	
Receive Group Delay	tgd R2	600			_	0.00	0.35	
	tgd R3	1000	0		_	0.00	0.125	ms
	tgd R4	2600			_	0.09	0.125	
	tgd R5	2800			_	0.12	0.75	
Crosstalk Attenuation	CR T	1020	0	$TRANS \to RECV$	75	85	_	40
OI USSIAIN MILEHUALIUH	CR R	1020	U	$RECV \to TRANS$	70	80	_	dB

^{*1} Psophometric filter is used

^{*2} Upper is specified for the MSM7578H, lower for the MSM7579

^{*3} MSM7578H: All "1", MSM7579: "11010101"

^{*4} Minimum value of the group delay distortion

AC Characteristics (Continued)

 $(V_{DD} = +5 \text{ V } \pm 5\%, \text{ Ta} = -30^{\circ}\text{C to } +85^{\circ}\text{C})$

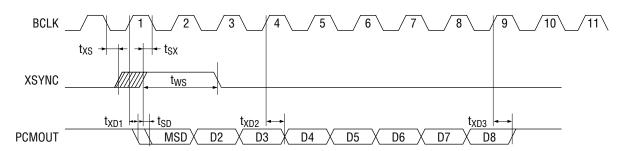
Parameter	Symbol	Freq. (Hz)	Level (dBm0)	Condition	Min.	Тур.	Max.	Unit
Discrimination	DIS	4.6 kHz to 72 kHz	0	0 to 4000 Hz	30	32	_	dB
Out-of-band Spurious	S	300 to 3400	0	4.6 kHz to 100 kHz	_	-37.5	-35	dBm0
Intermodulation Distortion	IMD	fa = 470 fb = 320	-4	2fa – fb	_	-52	-35	dBm0
Power Supply Noise Rejection Ratio	PSR T PSR R	0 to 50 kHz	50 mV _{PP}	*5	_	30	_	dB
	t _{SD}				20	_	200	
Digital Output Delay Time	t _{XD1}	C. 100 r	\E		20		200	
	t _{XD2}	CL = 100	$C_L = 100 \text{ pF}$			_	200	ns
	t _{XD3}				20	_	200	

^{*5} The measurement under idle channel noise

TIMING DIAGRAM

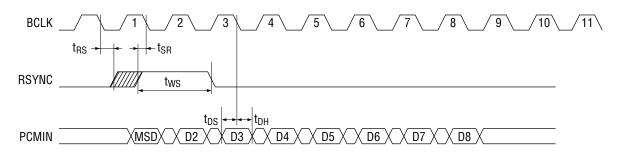
PCM Data Input/Output Timing

Transmit Timing

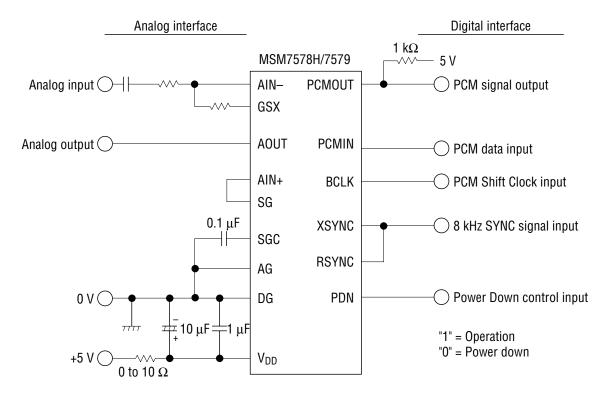


When $t_{XS} \le 1/2 \bullet Fc$, the Delay of the MSD bit is defined as t_{XD1} . When $t_{SX} \le 1/2 \bullet Fc$, the Delay of the MSD bit is defined as t_{SD} .

Receive Timing



APPLICATION CIRCUIT



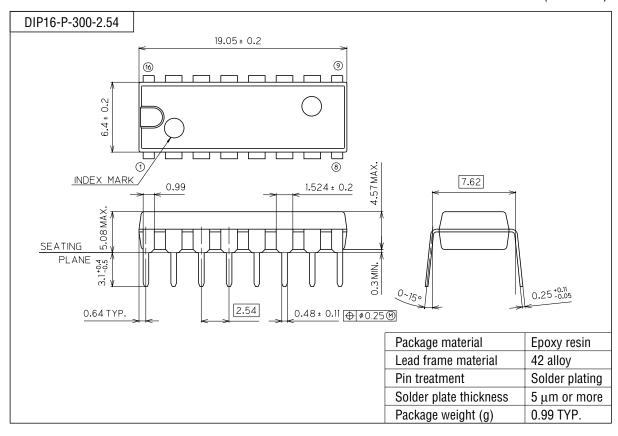
The analog output signal has an amplitude of ± 1.2 V above and below the offset voltage level of $V_{DD}/2$.

RECOMMENDATIONS FOR ACTUAL DESIGN

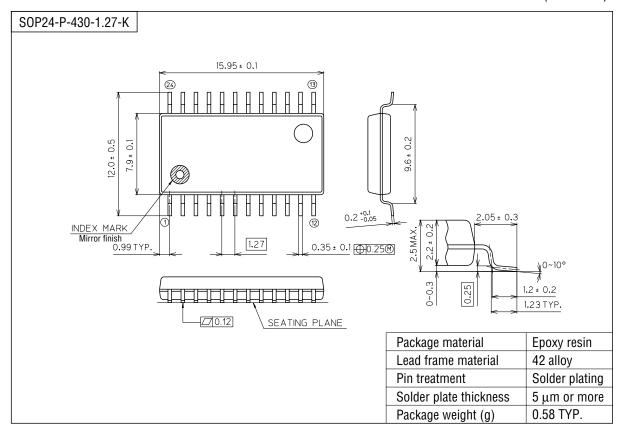
- To assure proper electrical characteristics, use bypass capacitors with excellent high frequency characteristics for the power supply and keep them as close as possible to the device pins.
- Connect the AG pin and the DG pin each other as close as possible. Connect to the system ground with low impedance.
- Mount the device directly on the board when mounted on PCBs. Do not use IC sockets. If an IC socket is unavoidable, use the short lead type socket.
- When mounted on a frame, use electro-magnetic shielding, if any electro-magnetic wave source such as power supply transformers surround the device.
- Keep the voltage on the V_{DD} pin not lower than –0.3 V even instantaneously to avoid latchup phenomenon when turning the power on.
- Use a low noise (particularly, low level type of high frequency spike noise or pulse noise) power supply to avoid erroneous operation and the degradation of the characteristics of these devices.

PACKAGE DIMENSIONS

(Unit: mm)



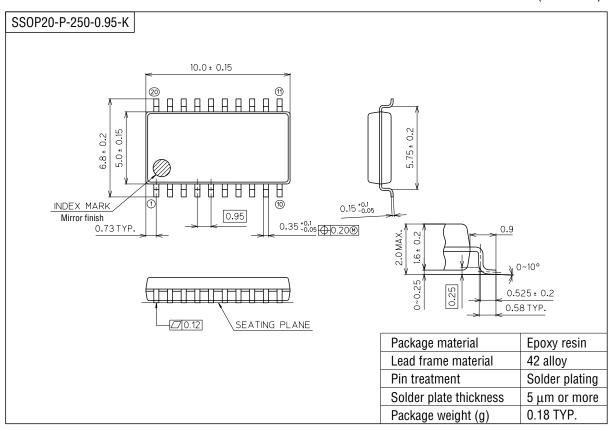
(Unit: mm)



Notes for Mounting the Surface Mount Type Package

The SOP, QFP, TSOP, SOJ, QFJ (PLCC), SHP and BGA are surface mount type packages, which are very susceptible to heat in reflow mounting and humidity absorbed in storage. Therefore, before you perform reflow mounting, contact Oki's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

(Unit: mm)



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